

REMARKS

This case has been carefully reviewed and analyzed in view of the Official Action dated June 19, 2003.

The Examiner has objected to claim 4 because of informalities. Claim 4 has been amended to overcome this objection.

Further, the Examiner has rejected claim 4 under 35 U.S.C. 102(b) as being anticipated by Kuno et al., U.S. Patent Application Publication No. 2002/0145676. Furthermore, the Examiner has rejected claim 4 under 35 U.S.C. 102(b) as being anticipated by Shinomiya, U.S. Patent Application Publication No. 2001/005073. However, it is respectfully requested that this rejection be withdrawn in light of the following reasons.

Kuno et al, the first reference cited by the Examiner, discloses an image pickup apparatus which is related to an image pickup apparatus that does not require a focus-adjusting mechanism for an optical system. However, this reference fails to disclose or teach a structure of a chip package for a digital photographic lens device having a lens device assembly, a flexible circuit board and a hard thin plate, said assembly includes a top housing, a lens in said top housing, a chip mounted under said top housing, said assembly being mounted on said flexible circuit board, said flexible circuit board being connected to a back panel of said digital photographic lens device and being mounted with said hard thin plate to provide supporting strength and insulation of connection thereof, said hard thin plate being mounted on a bottom of said flexible circuit board, said flexible circuit board having electrically conductive connection points printed onto a continuation strap body so that said flexible circuit board is pre-fabricated and packed into a reel, facilitating production process, a surface of said flexible circuit board being a layout with flexible electrical connection circuit of related circuit. Hence, this reference can be clearly

distinguished from the present invention.

Shinomiya, the second reference cited by the Examiner, discloses a solid state imaging apparatus. Nevertheless, as the previous cited reference, the Shinomiya reference still fails to teach or suggest a structure of a chip package for a digital photographic lens device having a lens device assembly, a flexible circuit board and a hard thin plate, said assembly includes a top housing, a lens in said top housing, a chip mounted under said top housing, said assembly being mounted on said flexible circuit board, said flexible circuit board being connected to a back panel of said digital photographic lens device and being mounted with said hard thin plate to provide supporting strength and insulation of a connection thereof, said hard thin plate being mounted on a bottom of said flexible circuit board, said flexible circuit board having electrically conductive connection points printed onto a combination continuation strap body so that said flexible circuit board is pre-fabricated and packed into a reel, facilitating production process, a surface of said flexible circuit board being a layout with flexible electrical connection circuit of related circuit. Consequently, this reference is in no way similar to the present invention.

Accordingly, the cited references fails to teach each and every element of the claimed invention and so the subject matter sought to be patented as a whole would not have been obvious to one of ordinary skill in the art.

It is now believed that the subject Patent Application has been placed in condition of allowance, and such action is respectfully requested.

Respectfully submitted,



Signature

Chih-Yu Ting (October 20, 2003)